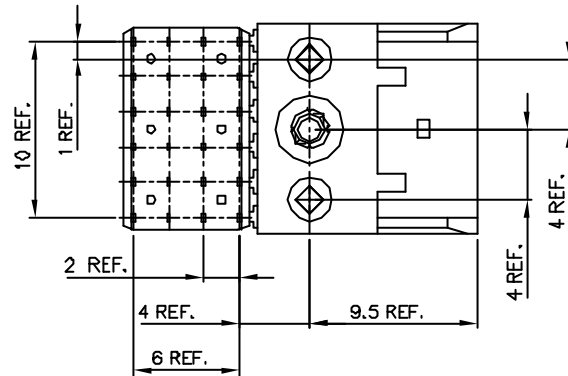
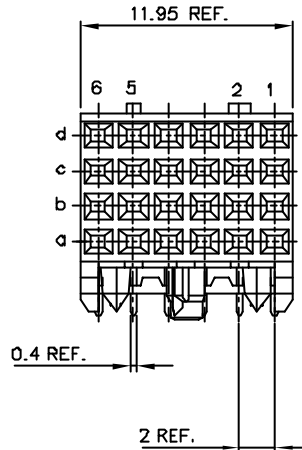
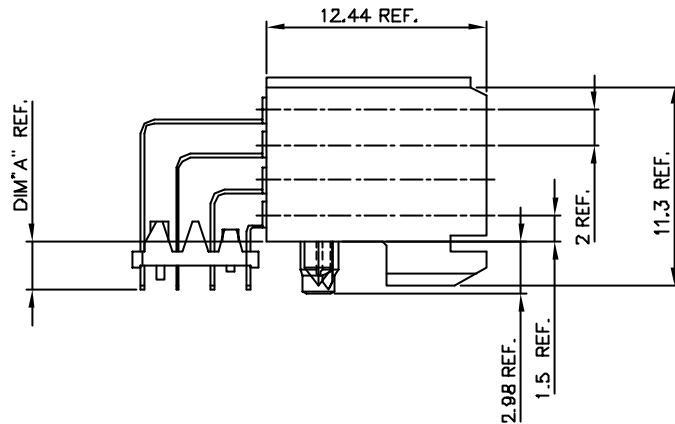
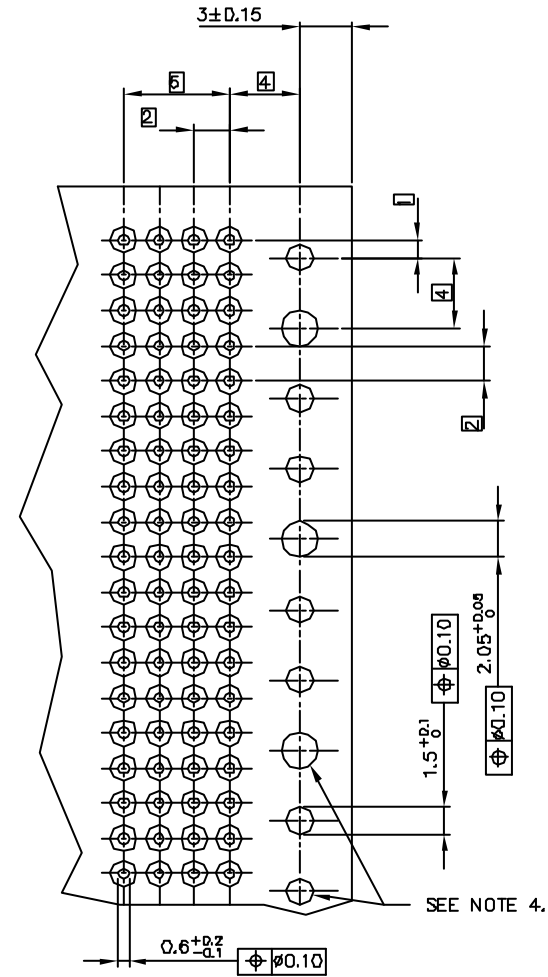
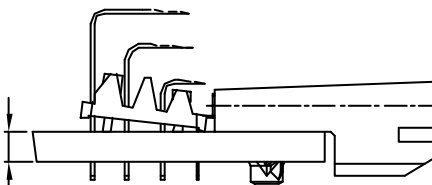


PC BOARD VERSIONS		
PRODUCTNR.	PCB THICKNESS	DIM"A"
89035-X01	1.6	2.73
89035-X11	2.4	3.53
89035-X01LF	1.6	2.73
89035-X11LF	2.4	3.53



PRODUCT AFTER PC BOARD APPLICATION.

PC BOARD THICKNESS ±0.20
SEE TABLE



RECOMMENDED HOLE PATTERN, COMPONENT SIDE.

NOTES:

- 1 BODY MAT'L: LIQUID CRYSTAL POLYMER 30% GLASS
FLAME RETARDANT ACC. UL 94-V0
- 2 TERMINAL MATERIAL: PHOSPHOR BRONZE.
- 3 PLATING SOLDER TAILS 2-8 µm SnPb 90-97 OR 2-8 µm PURE Sn FOR LEAD FREE .
- 4 INDICATED HOLES ARE UNPLATED.
- 5 PRODUCT MARKING: PARTNUMBER & BATCH ID.
- 6 THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN CS-22-00B .
- 7 THE HOUSING WILL WITHSTAND EXPOSURE TO 260DEGREE PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION.

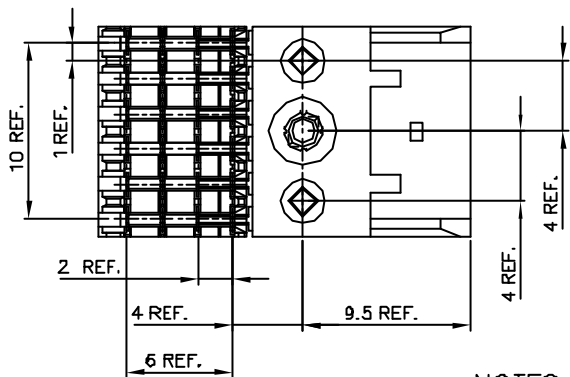
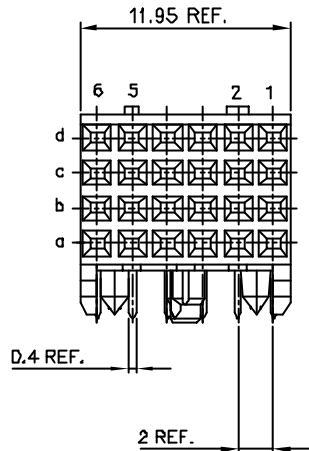
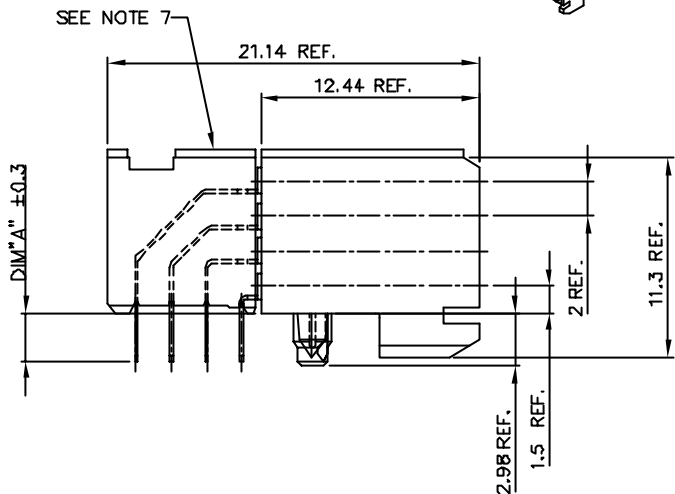
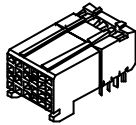
PRODUCT NR:	PLATING CONTACT AREA:	UNDERPLATING
89035-1YZLF	0.8 µm GOLD	1.3 µm Ni MIN.
89035-2YZLF	2 µm GOLD	1.3 µm Ni MIN.
89035-3YZLF	1.3 µm GOLD	1.3 µm Ni MIN.
89035-9YZLF	0.8 µm GXT	1.3 µm Ni MIN.
89035-1YZ	0.8 µm GOLD	1.3 µm Ni MIN.
89035-2YZ	2 µm GOLD	1.3 µm Ni MIN.
89035-3YZ	1.3 µm GOLD	1.3 µm Ni MIN.
89035-9YZ	0.8 µm GXT	1.3 µm Ni MIN.

mat'l code		tolerances unless otherwise specified		CUSTOMER	
itr	ean no	dr	date	CDPY	RA FEMALE SIGNAL
H	8004-0104	CU	041220	linear	12 mm PRESS PEC
C	H4018	EFE	040211	angles	product family METRAL (tm)
D	H4038	008	040527	dr	code
E	V7078	008	070602	eng	213
F	V00078	LLA	000318	chr	size dwg no
G	V00047	LLA	000330	appl	89035
sheet	revision	H	H	scale	1 of 2
index	sheet	1	2	Dr:1	

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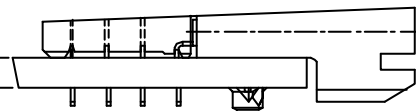
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PC BOARD VERSIONS		
PRODUCTNR:	PCB THICKNESS	DIM"A"
89035-X02	1.6	2.73
89035-X12	2.4	3.53
89035-X02LF	1.6	2.73
89035-X12LF	2.4	3.53

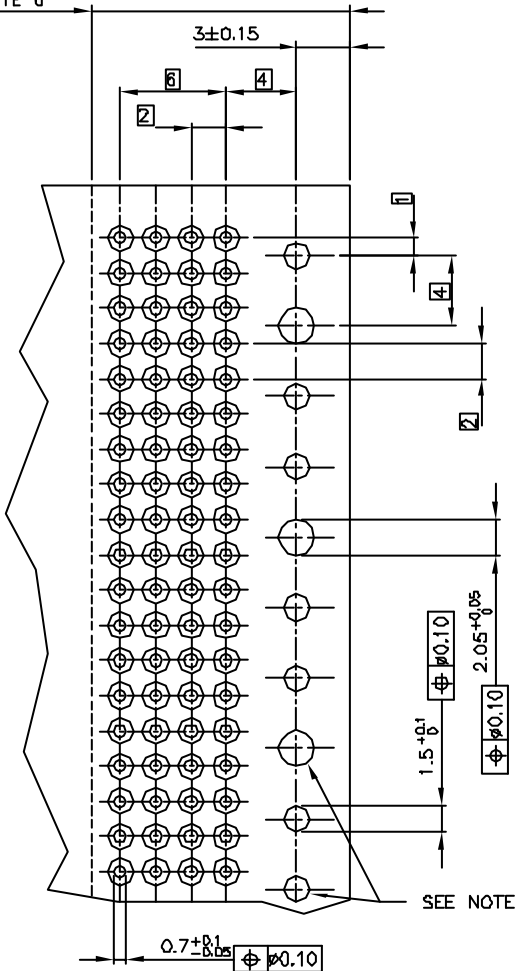


PRODUCT AFTER PC BOARD APPLICATION.

PC BOARD THICKNESS ±0.20
SEE TABLE



14.64 REF. SEE NOTE 6



RECOMMENDED HOLE PATTERN, COMPONENT SIDE.

NOTES:

- BODY MAT'L: LIQUID CRYSTAL POLYMER 30% GLASS FLAME RETARDANT ACC. UL 94-V0
- TERMINAL MATERIAL: PHOSPHOR BRONZE.
- PLATING SOLDER TAILS 2-8 µm SnPb 90-97 OR 2-8 µm PURE Sn
- INDICATED HOLES ARE UNPLATED.
- PRODUCT MARKING: PARTNUMBER & BATCH ID.
- SET BACK FOR PRESS BLOCK.
- TOP SURFACE OF PRESS BLOCK MAY EXTEND UP TO 0.4MM HIGHER THAN HOUSING. THIS MAY AFFECT THE TAIL LENGTH BEFORE APPLICATION TO A BOARD.
- THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-00B.
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260 DEGREE PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION.

PRODUCT NR:	PLATING CONTACT AREA:	UNDERPLATING
89035-1YZLF	0.8 µm GOLD	1.3 µm Ni MIN.
89035-2YZLF	2 µm GOLD	1.3 µm Ni MIN.
89035-3YZLF	1.3 µm GOLD	1.3 µm Ni MIN.
89035-9YZLF	0.8 µm GXT	1.3 µm Ni MIN.
89035-1YZ	0.8 µm GOLD	1.3 µm Ni MIN.
89035-2YZ	2 µm GOLD	1.3 µm Ni MIN.
89035-3YZ	1.3 µm GOLD	1.3 µm Ni MIN.
89035-9YZ	0.8 µm GXT	1.3 µm Ni MIN.

mat'l code		tolerances unless otherwise specified		CUSTOMER GDY		ELECTRONICS	
tr	san no	dr	date	linear	projection	RA FEMALE SIGNAL	
H				angles	1:1	12 mm PRESS PEG	
		dr	0. de an	mm	product family	ETRAL(um)	code
		eng	P. Scholt	070529	size	dwg no	213
		chr	P. Scholt	070529	scale	8:1	89035
		appl	Doc/mana	070529	sheet		2 of
sheet index	revision sheet						

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